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ARCHITECTURE FOR STANDALONE AND
SCALABLE LIQUID COOLING MODULES**

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(57) **ABSTRACT**

Multiple systems for providing liquid and air cooling for IT components is disclosed. The system includes a first module with at least one dry cooler that supplies liquid cooling to at least one liquid heat exchange device. The system includes a second module with the at least one liquid heat exchange device that provides liquid cooling to a third module comprising one or more IT units. The third module includes one or more cooling lines in a space beneath a floor that provides liquid cooling to the one or more IT units, with at least one removable floor panel, and one or more shock isolation components for the one or more cooling lines.

